

01-17-2002

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101950806 COVER SHEET
PATENTS ONLY

TO: The Commissioner of Patents and Trademarks: Please record the attached original document(s) or copy(ies).

Submission Type	Conveyance Type
<input checked="" type="checkbox"/> New	<input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Security Agreement
<input type="checkbox"/> Resubmission (Non-Recordation) Document ID#	<input type="checkbox"/> License <input type="checkbox"/> Change of Name
<input type="checkbox"/> Correction of PTO Error Reel # Frame #	<input type="checkbox"/> Merger <input type="checkbox"/> Other
<input type="checkbox"/> Corrective Document Reel # Frame #	U.S. Government (For use ONLY by U.S. Government Agencies)
	<input type="checkbox"/> Departmental File <input type="checkbox"/> Secret File
Conveying Party(ies)	<input type="checkbox"/> Mark if additional names of conveying parties attached

Execution Date
Month Day YearName (line 1) **OSG-LA, Inc.**

October 18, 2001

Name (line 2) a corporation of the State of Delaware

Second PartyExecution Date
Month Day Year

Name (line 1)

Name (line 2)

Receiving Party

Mark if additional names of receiving party attached

Name (line 1) **Wabash Technologies, Inc.**

Name (line 2)

Address (line 1) 1375 Swan Street

Address (line 2)

☐ If document to be recorded is an assignment and the receiving party is not domiciled in the United States, an appointment of a domestic representative is attached. (Designation must be a separate document from Assignment.)

Address (line 3) Huntington

Indiana

46750

City

State/Country

Zip Code

Domestic Representative Name and Address

Enter for the first Receiving Party only.

Name

Address (line 1)

Address (line 2)

Address (line 3)

Address (line 4)

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200.00 DP

Mail documents to be recorded with required cover sheet(s) information to:
Commissioner of Patents and Trademarks, Box Assignments, Washington D.C., 20231**PATENT**
REEL: 012461 FRAME: 0001

Page 2

Correspondent Name and Address

(317) 634-3456 Telephone

Name **Brad A. Schepers**Address (line 1) **Woodard, Emhardt, Naughton, Moriarty & McNett**Address (line 2) **111 Monument Circle, Suite 3700**Address (line 3) **Bank One Center/Tower**Address (line 4) **Indianapolis, Indiana 46204-5137**

Pages Enter the total number of pages of the attached conveyance document including any attachments.

#3

Application Number(s) or Patent Number(s)☐ Mark if additional numbers attached

Enter either the Patent Application Number or the Patent Number (DO NOT ENTER BOTH numbers for the same property).

Patent Application Number(s)**Patent Number(s)**

09/721,227

5,053,283

5,702,653

5,169,465

5,652,562

If this document is being filed together with a new Patent Application, enter the date the patent application was signed by the first named executing inventor.

Month Day Year

Patent Corporation TreatyEnter a PCT application number only if a U.S. Application Number has not been assigned.

PCT

PCT

PCT

PCT

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Number of properties

Enter the total number of properties involved

5

Fee Amount

Fee Amount for Properties Listed (37 CFR 3.41):

\$ 200.00

Method of Payment:
Deposit Account☒ Enclosed (Check)☐ Deposit Account

(Enter for payment by deposit account or if additional fees can be charged to the account).

Deposit Account Number

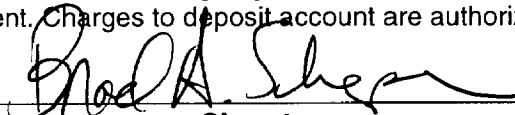
#23-3030

Authorization to charge additional fees:

Yes ☒No ☐**Statement and Signature**

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Charges to deposit account are authorized, as indicated herein.

Brad A. Schepers, Reg. No. 45,431



December 10, 2001

Name of Person Signing

Signature

Date

NUNC PRO TUNC ASSIGNMENT

WHEREAS, **OSG-LA, Inc.**, hereinafter referred to as Assignor, a corporation of the State of Delaware, having an address of 565 Fifth Avenue, Fourth Floor, New York, New York 10017, was the owner until July 31, 2001 of the patents and patent applications identified in the APPENDIX attached hereto and incorporated herein (hereinafter INTELLECTUAL PROPERTY); and

WHEREAS, **Wabash Technologies, Inc.**, hereinafter referred to as Assignee, a corporation of the State of Delaware, having a principal place of business at 1375 Swan Street, Huntington, Indiana 46750, acquired all the assets of Assignor on July 31, 2001, said assets including all right, title and interest in, to and under said INTELLECTUAL PROPERTY;

WHEREAS, it is desired to confirm the aforesaid transfer of said INTELLECTUAL PROPERTY and to make the same a matter of record in the U.S. Patent and Trademark Office and in certain foreign patent offices;

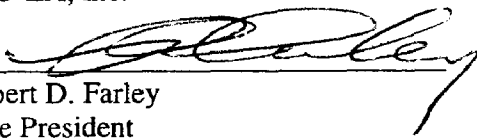
NOW, THEREFORE, to all whom it may concern, be it known that for and in consideration of the sum of One Dollar (\$1.00) and other good, valuable and sufficient considerations to Assignor in hand paid, the receipt of which is hereby acknowledged, Assignor hereby acknowledges the aforesaid transfer, and by these presents does sell, assign and transfer unto Assignee all right, title and interest in, to and under said INTELLECTUAL PROPERTY, including the inventions disclosed, described and claimed or intended so to be in said patents and applications, any and all applications thereon and arising therefrom, including any and all divisions and continuations thereof, and any and all patents to be issued and obtained therefor and thereon, United States and foreign, including all reissues and extensions thereof;

Assignor agrees to assign and execute any and all other papers necessary or desirable for the procurement of Letters Patents on said INTELLECTUAL PROPERTY in this and all foreign countries for the use of Assignee.

This assignment shall be, and is hereby made, effective *nunc pro tunc* as of July 31, 2001.

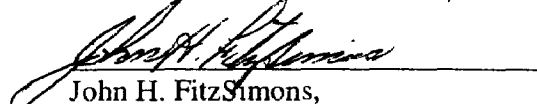
IN WITNESS WHEREOF, Assignor & Assignee have caused this Assignment to be executed by their duly authorized representatives on the dates indicated below.

OSG-LA, Inc.


Robert D. Farley
Vice President

October 18, 2001
Date

WABASH TECHNOLOGIES, INC.


John H. FitzSimons,
Secretary

October 18, 2001
Date

STATE OF NEW YORK)
COUNTY OF NEW YORK) SS:

Before me, a Notary Public in and for said County and State, personally appeared the above-named Robert D. Farley, who executed the foregoing Assignment in my presence and acknowledged his authority to do so on behalf of OSG-LA, Inc.

Dawn E. Roberts
Notary Public

My Commission Expires:
7-17-03

Printed: DAWN E. Roberts
Resident of New York County

DAWN E. ROBERTS
Notary Public, State of New York
No. 01RO5046850
Qualified in New York County 03
Commission Expires July 17, 2003

STATE OF NEW YORK)
COUNTY OF NEW YORK) SS:

Before me, a Notary Public in and for said County and State, personally appeared the above-named John H. FitzSimons, who executed the foregoing Assignment in my presence and acknowledged his authority to do so on behalf of Wabash Technologies, Inc.

Dawn E. Roberts
Notary Public

My Commission Expires:
7-17-03

Printed: DAWN E. Roberts
Resident of New York County

DAWN E. ROBERTS
Notary Public, State of New York
No. 01RO5046850
Qualified in New York County 03
Commission Expires July 17, 2003

APPENDIX

U.S. PATENTS

Patent No.	Issue Date	Title
5,053,283	October 1, 1991	THICK-FILM INK COMPOSITION
5,702,653	December 30, 1997	THICK-FILM CIRCUIT ELEMENT
5,169,465	December 8, 1992	THICK-FILM CIRCUIT ELEMENT ON A CERAMIC SUBSTRATE
5,652,562	July 29, 1997	THERMALLY FUSED RESISTOR HAVING A PORTION OF A SOLDER LOOP THERMALLY CONNECTED TO AN ELECTRICALLY INSULATED PORTION OF AN OUTER SURFACE OF THE RESISTOR

U.S. PATENT APPLICATIONS

Application Serial No.	Filing Date	Title
09/721,227	November 22, 2000	MAGNETIC NON-CONTACTING ROTARY TRANSDUCER

FOREIGN PATENTS

Country	Patent No.	Issue Date	Title
Australia	725,850	February 1, 2001	THERMALLY FUSED RESISTOR
Singapore	60594	March 21, 2000	THERMALLY FUSED RESISTOR

FOREIGN PATENT APPLICATIONS

Country	Application Serial No.	Filing Date	Title
Canada	2,174,292	April 16, 1996	THICK-FILM CIRCUIT ELEMENT
Europe	96301879.1	March 19, 1996	THICK-FILM CIRCUIT ELEMENT
Japan	83504/96	April 5, 1996	THICK-FILM CIRCUIT ELEMENT
Brazil	PI9709592-3	May 21, 1997	THERMALLY FUSED RESISTOR
Canada	2,255,587	May 21, 1997	THERMALLY FUSED RESISTOR
China	97196304.5	May 21, 1997	THERMALLY FUSED RESISTOR
Europe	97927685.4	May 21, 1997	THERMALLY FUSED RESISTOR
Hong Kong	00101542.1	March 13, 2000	THERMALLY FUSED RESISTOR
Japan	542683/97	May 21, 1997	THERMALLY FUSED RESISTOR
Mexico	989646	May 21, 1997	THERMALLY FUSED RESISTOR
Slovakia	PV 1599-98	May 21, 1997	THERMALLY FUSED RESISTOR